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Agenda

- PCB array
- Copper price development and choice of materials
- PCB stackup
- Mechanical processing
- **M** Advanced technologies
- More tips & tricks
- **Summary**



Jürgen Wolf

Würth Elektronik GmbH & Co. KG Head of Advanced Solution Center



Agenda



Copper price development and choice of materials

PCB stackup

Mechanical processing

Advanced technologies

More tips & tricks

Summary



How to utilize and occupy the manufacturing panel properly?

The Key Factor: How is the manufacturing panel occupied with PCBs?

- Background information:
 - PCB materials are manufactured in large panels
 90% of EU and US manufacturers of FR4 uses these formats:

• US-Format: 1.225 x 925 mm²

• Uni-Format: 1.225 x 1.070 mm²

95% of PCB manufacturers in EU & US use these panel formats:

• 460 x 305 mm² (1/8 US-Format) WE sample format

606 x 458 mm² (1/4 US-Format) WE standard format

606 x 528 mm² (1/4 Uni-Format) WE jumbo format

606 x 458 mm² × 460 x 305 mm²

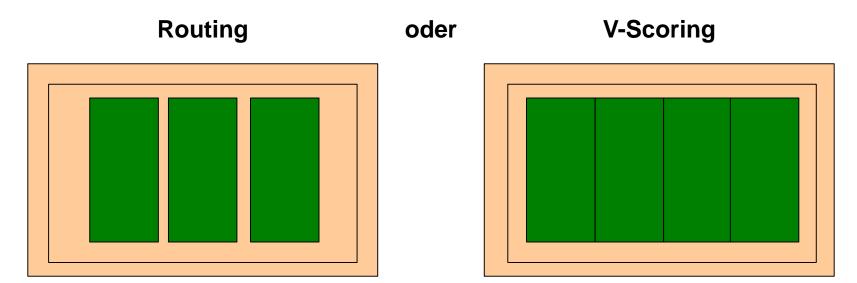


How to utilize and occupy the manufacturing panel properly?

The Key Factor: How is the manufacturing panel occupied with PCBs?

Every PCB manufacturer needs a border for registration and labeling ⇒ Non-useable space!

Example: Single PCBs



In this example: 33% more circuit boards on the production panel





The Key Factor: How is the manufacturing panel occupied with PCBs?

Every PCB manufacturer needs a border for registration and labeling ⇒ Non-useable space!

Example: Single PCBs – The smaller the PCB, the greater the effect!

Routing	or	V-Scoring
Fertigungsformat RAS 480,00 * 305,00 Fertigungsnutzen RT [RT]		Fertigungsformat RAS 460,00 * 305,00 Fertigungsnutzen RT [RT]
		•
		•

In this example: 56 PCBs vs. 85 PCBs

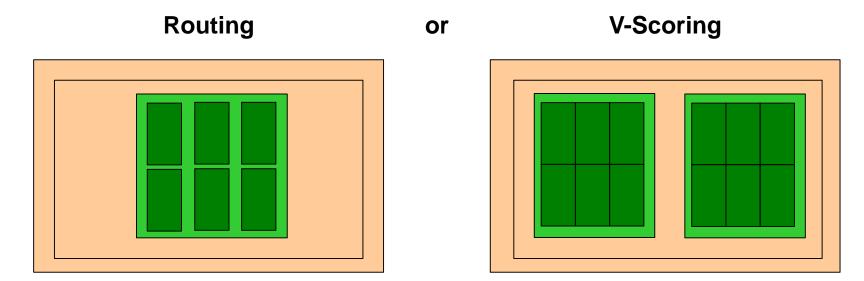


How to utilize and occupy the manufacturing panel properly?

The Key Factor: How is the manufacturing panel occupied with PCBs?

Every PCB manufacturer needs a border for registration and labeling ⇒ Non-useable space!

Example: PCBs in array



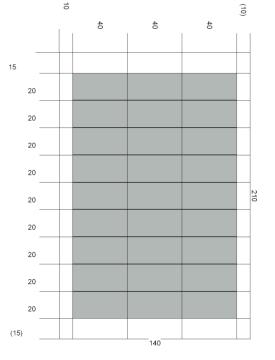
In this example: 100% more circuit boards on the production panel

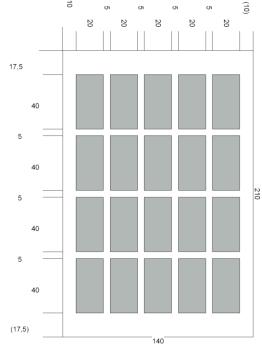
How to utilize and occupy the manufacturing panel properly?

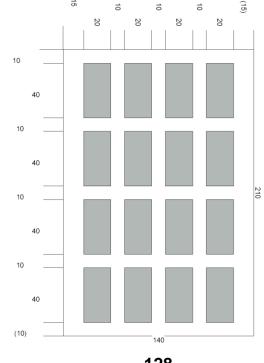


Calculation Basis:

- ML6 / Base Material T_g150
- PCB size 20 x 40 mm²
- Array size 210 x 140 mm²
- 100 μ m L/S
- 500 drills
- 0,20 mm smallest drill-Ø
- ENIG







PCBs	on a	production	panel
. 503	011 0	production	Paric

Number of production panels (1.000 PCBs ordered)

PCBs in an array

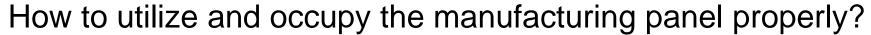
PCB outline

PCB distance in array

Price indicator



0,00 mm **100%** 160 7 20 routed 5,00 mm 117% 128 8 16 routed 10,00 mm 131%





The Key Factor: How is the manufacturing panel occupied with PCBs?

WE-Format		Sample format	Standard format	Jumbo format
Technologies		All technologies	Basic, flex-rigid & HDI	Basic & HDI
Plant		Rot am See	Niedernhall	Schopfheim
			Used in Schopfheim for special constructions	Niedernhall on demand
Panel size		460 x 305 mm ²	606 x 458 mm ²	606 x 528 mm ²
Usable area		426 x 271 mm ²	572 x 424 mm ²	570 x 500 mm ²
	Number of arrays	dimensions array		
Best array	1	426 x 271 mm ²	572 x 424 mm ²	570 x 500 mm ²
for	2	271 x 213 mm ²	424 x 286 mm ²	500 x 285 mm ²
V-scored outlines	4	213 x 135 mm ²	286 x 212 mm ²	285 x 250 mm ²
	6	142 x 135 mm ²	212 x 190 mm ²	250 x 190 mm ²
	8	135 x 106 mm ²	212 x 143 mm ²	250 x 142 mm ²
	9	142 x 90 mm ²	190 x 141 mm ²	190 x 166 mm ²
	12	106 x 90 mm ²	143 x 141 mm ²	166 x 142 mm ²
	15	90 x 85 mm ²	141 x 114 mm ²	166 x 114 mm ²

Tips:

- Edge of array edge min. 5 mm
- Edge of array 8 10 mm for routed outlines
- 2 edges with 5 10 mm for V-scored outlines
- Size of array should be based on thickness of PCB (the thinner the smaller)



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Development of copper prize

Role of material price in PCB price



Copper price:

Developments on the London commodity exchange

> Time period: Jan. 2016 until June 2020



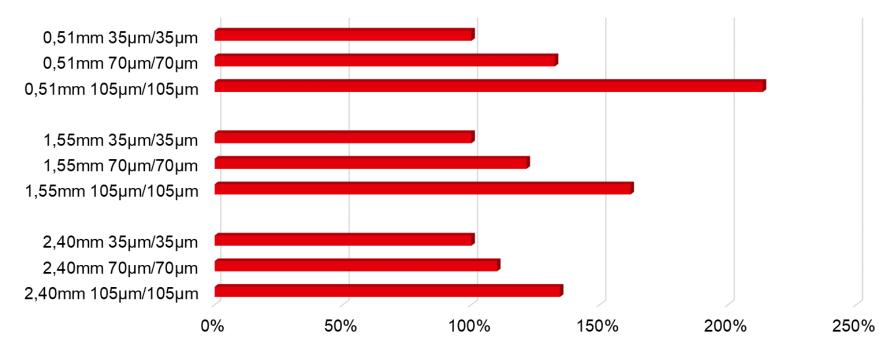
Source: http://www.boerse.de - data downloaded on 22.06.2020

Development of copper prize

Role of material price in PCB price



Comparison of material purchasing prices for FR4 T_g150 (as of July 2020)



Copper plays an important role in the price of PCBs!

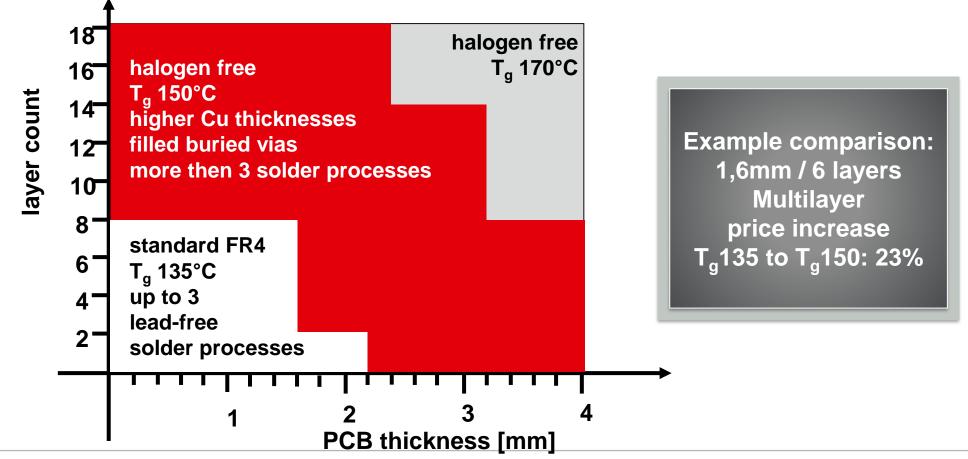
Hence the question: What is necessary or what is possible?

Choice of material

When to use which base material?



A small recommendation for the usage of base materials at Würth Elektronik





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Layer stackup

How does the PCB construction influence the price?



Comparison of a 4-layer multilayer with different thicknesses

Standard: 1,55 mm / 1,60 mm

Optimum: 1,00 mm

Further standards:

0,80mm / 2,00 mm / 2,40 mm



ML4 TG150 0.50 35

1x 0.10mm-035+035 4x prepreg 1080

Price indicator 107%



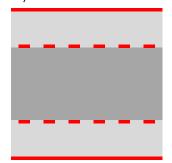


ML4_TG150_1.00_35

1x 0.41mm-035+035 4x prepreg 2116

Price indicator 96%

1,60mm



ML4_TG150_1.60_35

1x 0.71mm-035+035 4x prepreg 7628

Price indicator 100%

3,20mm



ML4_TG150_3.20_35

1x 2.40mm-035+035 4x prepreg 7628

Price indicator 137%

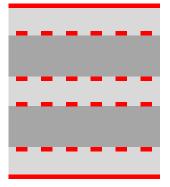
Layer stackup

How does the PCB construction influence the price?



Comparison of a 6-layer multilayer: 1,60 mm standard vs. individual stackup

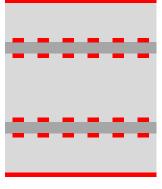
Standard stackup



2x 0.36mm-035+035 6x prepreg 2116

Price indicator 100%

Specific stackup



2x 0.10mm-035+035 2x prepreg 2116 8x prepreg 7628

Price indicator 116%

Additional costs:

- Handling thin laminate
- 4 prepregs more in stackup

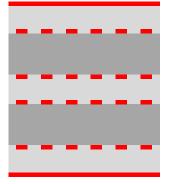
Layer stackup

How does the PCB construction influence the price?



Comparison of a 6-layer multilayer: 1,60 mm standard vs. individual stackup

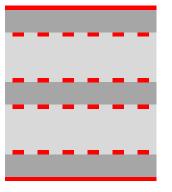
Standard stackup



2x 0.36mm-035+035 6x prepreg 2116

Price indicator 100%

Core-based stackup



3x 0.20mm-035+035 4x prepreg 2116 2x prepreg 7628

Price indicator 122%

Additional cost:

- Multiple exposure of the outer layer cores (process quasi like an 8layer PCB)
- More cores

Further cost drivers

Filling cores in stackup



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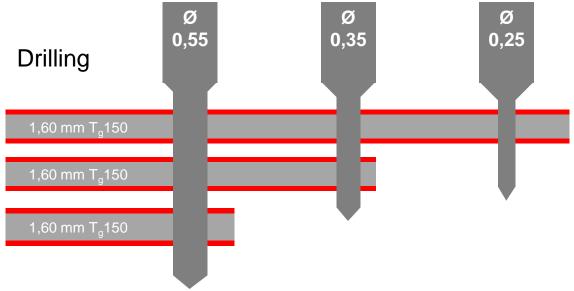
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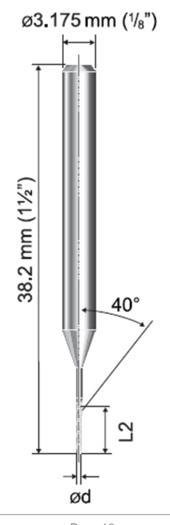
Which influence do the drilling tools have on the PCB costs?





Tool life
Panel stacking
Time to drill 15.000 vias
Usage of drill bits for 15.000 vias
Price indicator (only drilling process)

100%	200%	460%
4	7,5	30
0,2 h	0,4 h	0,8 h
1.250 strokes stack of 3	1.000 strokes stack of 2	500 strokes stack of 1



WÜRTH EI EKTRONI

Which influence do the drilling tools have on the PCB costs?

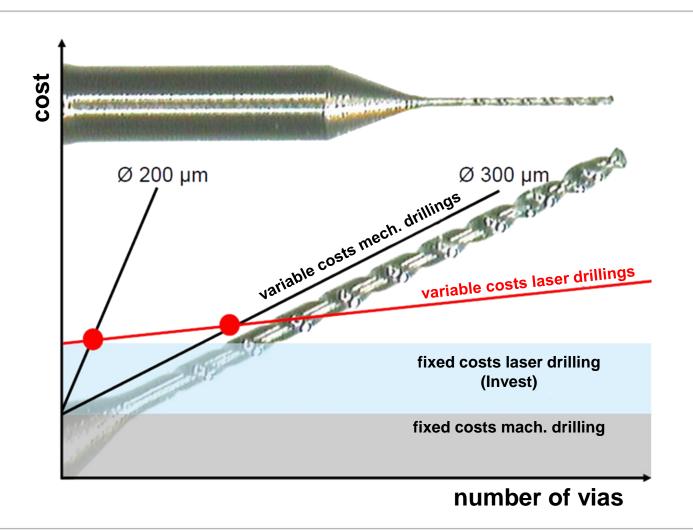
Comparison:

Ø 0,5 mm, Ø 0,35 mm und Ø 0,25 mm drill bits on 5 mm x 5 mm checkered paper



Which influence do the drilling tools have on the PCB costs?





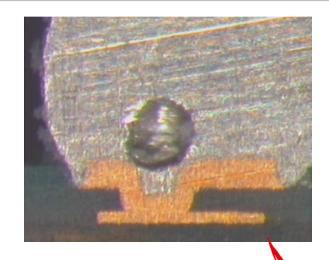
Ø 0,2 mm (0,55 € pro Bit) Tool life: 750 strokes Drilling frequency: 5 / s

Ø 0,3 mm (0,50 € pro Bit) Tool life: 1.000 strokes Drilling freq.: max. 8 / s

Microvia Ø 0,125 mm Drilling freq.: 150–180 / s

Filling of Microvias or not? That is the question!



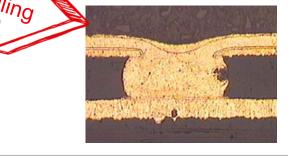


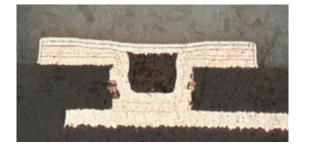
IPC-7095C - Table A-3 - Class III: Max. "22% of the image diameter"

The formation of voids depends, among other things, on:

- Flux / solder paste
- Temperature profile of the solder process
- Uniform heating or through-heating of the circuit board

Every user has to define for himself how to manufacture!

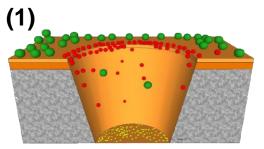




Filling of Microvias or not? That is the question!

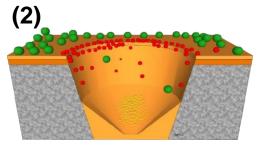


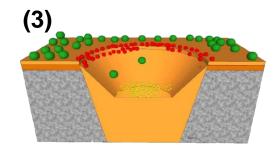
Sequence Cu-Filling Process (Source/publication: MacDermidEnthone Electronic Solutions / 2018)

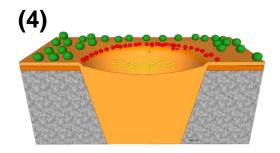




- Leveler
- Brightener





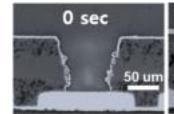


Role: Molecules occupy the surface and block the deposition of Cu

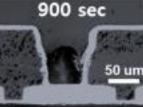
Role: Molecules accumulate at the location of the highest current densitiy and block the deposition of Cu

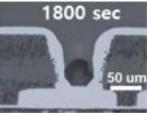
Role: Brightener for the reduction of Cu crystal sizes

Time sequence (Source/publication : KAIST / 2019)



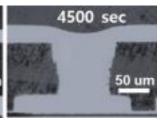
Legend:







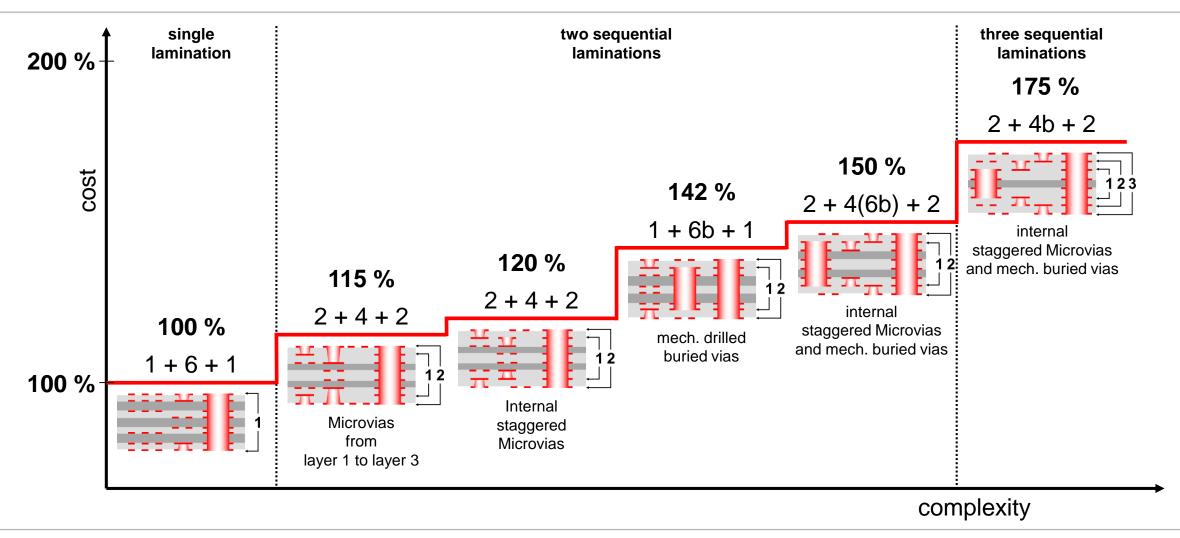




Process takes factor 2-3 longer compared to standard

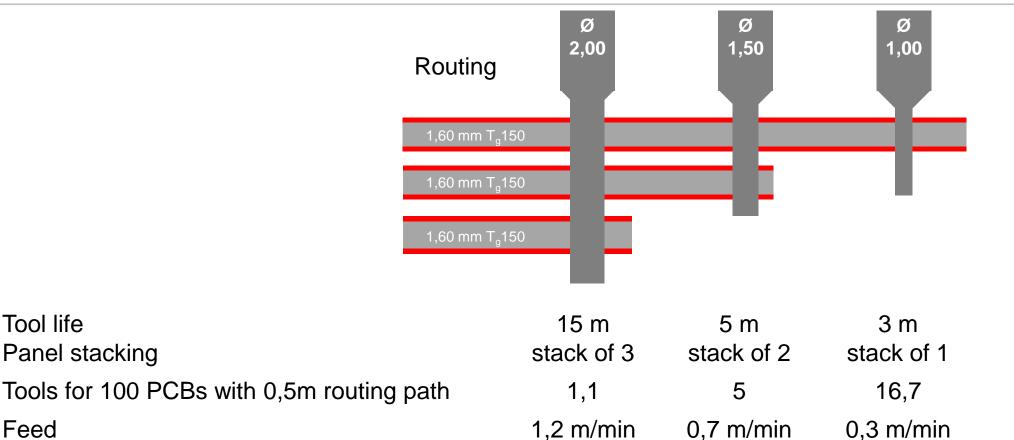
What influence does the HDI layer stackup have?





Which influence do the routing tools have on the PCB costs?





0,6 h

270%

2,8 h

1200%

0,2 h

100%

38.2 mm (1½") Ød

ø3.175 mm (1/8")

Tool life

Feed

Panel stacking

Time to route 100 PCBs with 0,5m routing path

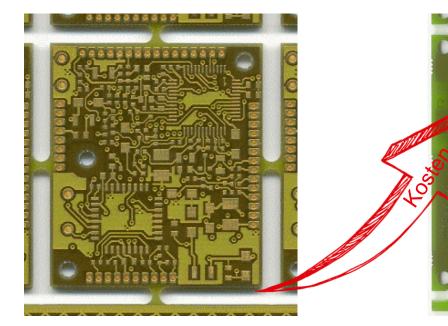
Price indicator (only routing process)

What else has an influence on the price of PCBs?



Routing contour

Complex routing contours can lengthen the routing paths and have a negative influence on the routing tool diameter



Standard routing contour

- 4x change in direction
- routing tool 2,4 mm

Complex routing contour

- approx. 30x change in direct.
- high routing time
- routing tool 1,8 mm



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What else has an influence on the price of PCBs?



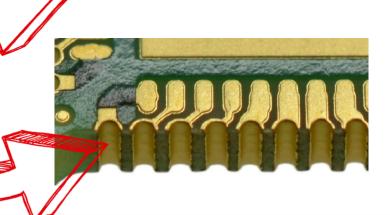
Further cost drivers!

PCB thickness / layer count⇒ not only relevant for drilling & routing....

Number of laminations

Edge plating / side plating

Castellated holes / Castellation



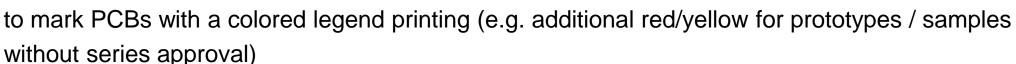
What else has an influence on the price of PCBs?



Further cost drivers!

Colored solder resist

- White / black / red / blue
- The problem: demand extremely low
- Question: Does it always have to be solder resist - or is it sufficient



Legend printing

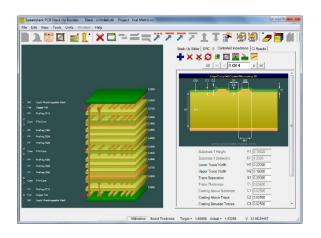
How small must be printed? Danger: printing onto pads

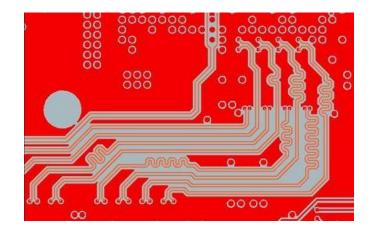


What else has an influence on the price of PCBs?



Required or needed impedances





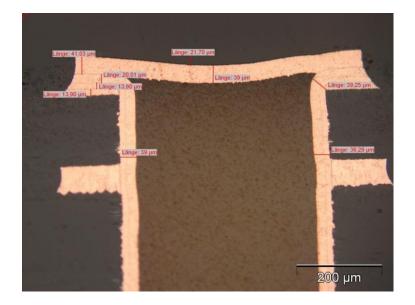
- Impedance watching / controlled dielectric
 - ⇒ Calculated stackup and tracks, no TDR coupons
- Impedance control
 - ⇒ additional TDR coupon (or coupons) on manufacturing panel
 - ⇒ reduced number of PCBS on manufacturing panel



What else has an influence on the price of PCBs?

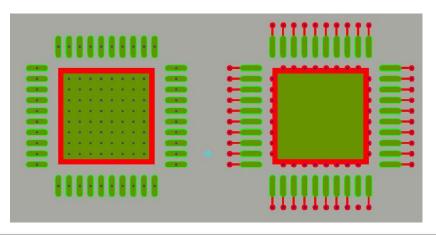


IPC 4761 – Filled and Capped Via (Type VII Via)
 ⇒ Via filled with resin and plated with Cu



Necessary or to be avoid with intelligent design?





What else has an influence on the price of PCBs?



Request: IPC Class 3

The requirement of $25\mu m$ copper in the barrel is often mistaken with the requirement of IPC Class 3 production:

- 25µm barrel copper is only a part of the requirement of IPC Class 3
- However, the stricter test criteria according to IPC Class 3 lead to a lower yield and, together with the effort to check the criteria, to an increased price!

What else has an influence on the price of PCBs?

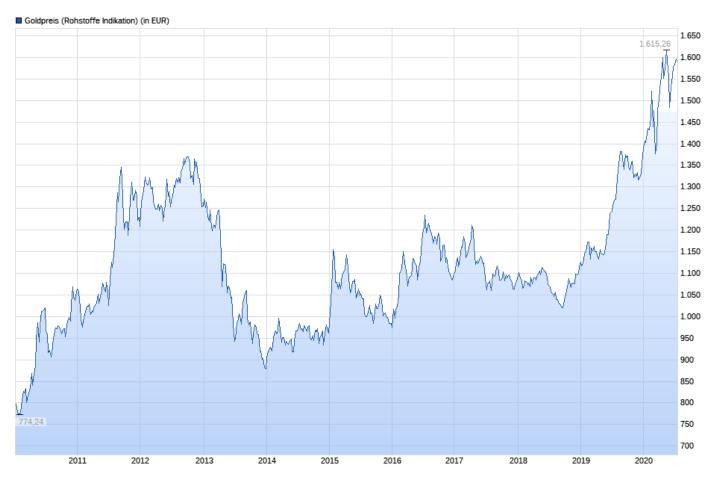


Electroplated Gold

Usage of electroplated Gold

- often used for contacts as an abrasion resistant surface
- mostly selective in combination with ENIG
- with thicknesses up to 4µm

Price indicator: up to 500% or more (depends on the current price of gold)

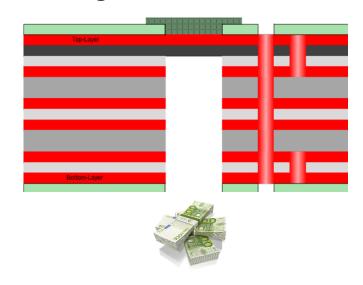


Source: http://www.boerse.de – data downloaded on 13.07.2020

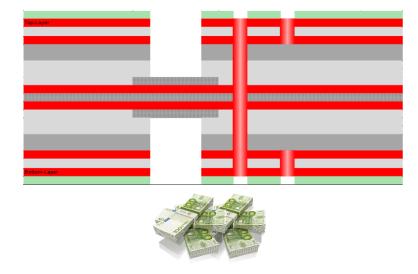
Who about flex-rigid stackups?



Flex-rigid 1F-5Ri / HDI 1-4-1



Flex-rigid 2Ri-2F-2Ri / HDI 1-4-1



- Single sided vs. double sided effort for mechanical depth milling
- Huge price differences for the flex material: copper on one or both sides
- Screen-printed flexible solder resist is cheaper than routed and laminated coverlay
- For higher reliability with xRi-2F-xRi: Partial coverlay (Bikini coverlay) required



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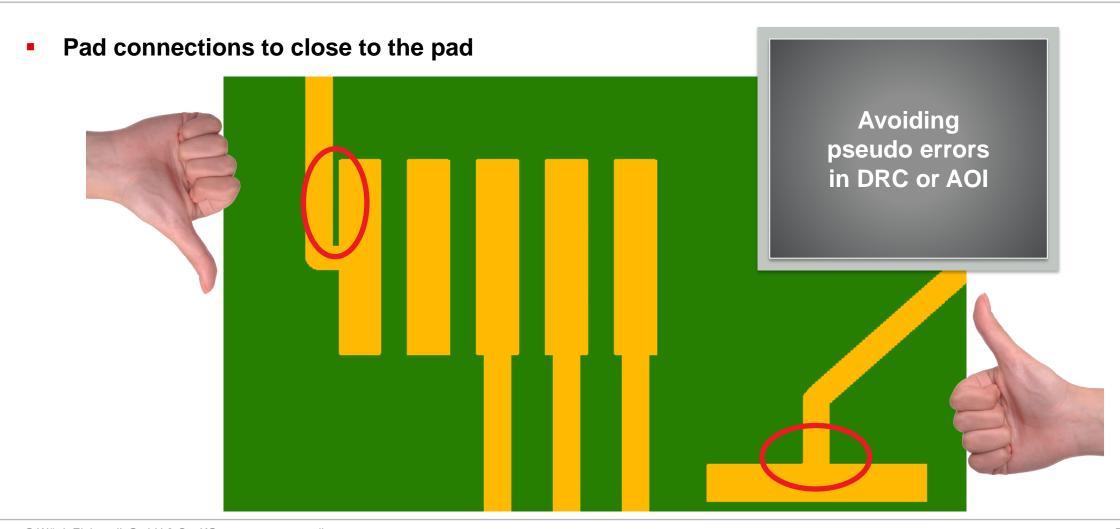
More tips & tricks

Summary

More tips & tricks

Error prevention



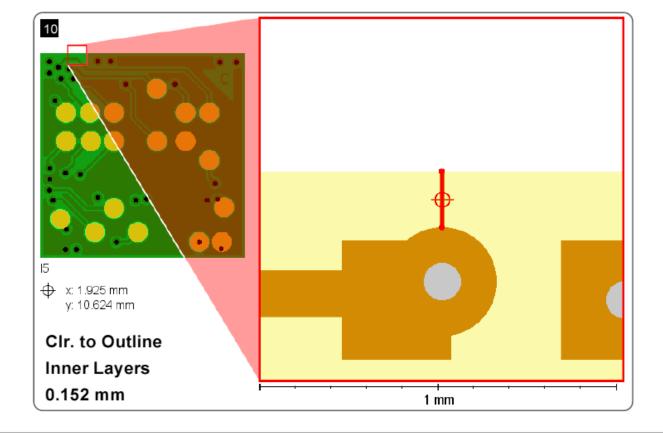


More tips & tricks

Error prevention



Clearance to outline of planes, lines and holes incl. pads



More tips & tricks

Data output – Gerber-Format



RS-274-D Standard Gerber

⇒ obsolete, replaced by

RS-274X Extended Gerber

Parameters for output:

- Often preset parameters are inaccurate in modern layouts:
 - 2.3 Inches ⇒ min. resolution 25,4 µm
 - Better: 2.5 Inches (min. resolution 0,254 μm) or
 - 4.4 metric (min. resolution 0,1 μm)
- No mixing of parameters:
 Drill data and Gerber data should be based on the same parameters due to tolerance chains in conversion of the data (especially for HDI boards)



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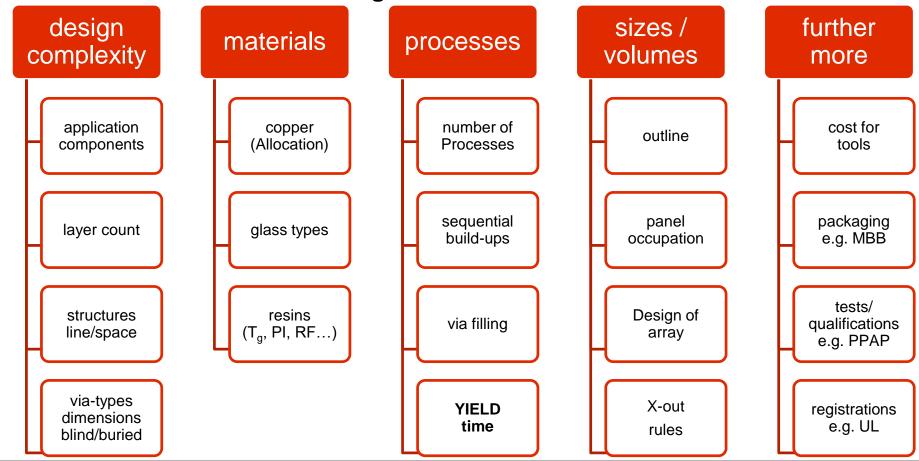
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Things to consider when manufacturing PCBs:



Thank you very much for your attention!



What kind of Application do you have?

HOW can WE

support YOU?

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